L Number	Hits	Search Text	DB	Time stamp
1	270	257/777.ccls. and wire and ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 18:50
3	27	((257/777.ccls. and wire and ball) and (@ad<20010330)) and capacitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 19:35
4	539	257/778.ccls. and wire and ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 18:50
6	38	((257/778.ccls. and wire and ball) and (@ad<20010330)) and capacitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 18:52
7	163	((chip or die) near capacitor) and wire and ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 18:52
8	117	(((chip or die) near capacitor) and wire and ball) and (@ad<20010330)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 18:54
9	113	((((chip or die) near capacitor) and wire and ball) and (@ad<20010330)) not (((257/778.ccls. and wire and ball) and (@ad<20010330)) and capacitor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 18:58
5	443	(257/778.ccls. and wire and ball) and (@ad<20010330)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 19:28
10	1	("6407456").PN.	USPAT	2003/04/13 19:28
11	32	((chip and substrate) near adhesive) and wire and ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 19:31
2	212	(257/777.ccls. and wire and ball) and (@ad<20010330)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 19:33